

## THE UNITED STATES PATENT AND TRADEMARK OFFICE

8-3-01 #3 IDS

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Applicant:

Pasqualoni et al.

AUG 3 2001

Serial No.:

09/845,549

**TECHNOLOGY CENTER R3700** 

Filed:

April 30, 2001

For:

CHEMICAL MECHANICAL POLISHING SLURRY

COMMPOSITION FOR POLISHING

Art Unit:

3723

Examiner:

Not yet assigned

**Attorney Docket:** 

341.6910USU

Commissioner for Patents Washington, D.C. 20231

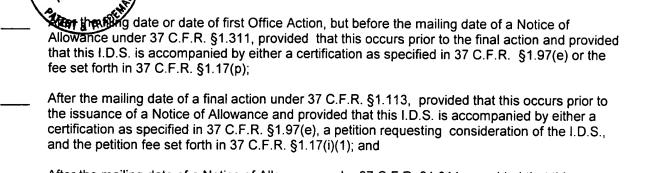
## **INFORMATION DISCLOSURE STATEMENT**

Sir:

In accordance with applicant's duty of disclosure under 37 C.F.R. §1.56, please find attached hereto form PTO-1449 listing information which may be material to the patentability of this application, filed April 30, 2001. This Information Disclosure .

Statement is being filed:

XXX	Within three (3) months of the filing date of the national application;
	Within three (3) months of the date of entry of the national stage as set forth in 37 C.F.R. §1.491 in an international application;
	Before the mailing date of a first Office Action on the merits;
	After the filing date or date of first Office Action, but before the mailing date of a final action under 37 C.F.R. §1.113, provided that this occurs prior to the issuance of a Notice of Allowance and provided that this I.D.S. is accompanied by either a certification as specified in 37 C.F.R. §1.97(e) or the fee set forth in 37 C.F.R. §1.17(p);



After the mailing date of a Notice of Allowance under 37 C.F.R. §1.311, provided that this occurs prior to the issuance of a final action and provided that this I.D.S. is accompanied by either a certification as specified in 37 C.F.R. §1.97(e), a petition requesting consideration of the I.D.S., and the petition fee set forth in 37 C.F.R. §1.17(I)(1).

Also enclosed are copies of the following U.S. Patents: 3,170,273; 3,527,028; 3 2001
4,050,954; 4,169,337; 4,304,575; 4,462,188; 5,139,571; 5,230,833; 5,246,624,00L0GY CENTER R3700
5,314,843; 5,340,370; 5,607,718; 5,66,097; 5,695,384; 5,750,440; 5,770,095;
5,908,509; 5,954,997; 5,980,775; 5,993,685; 5,996,595; and 6,010,962. Also enclosed are copies of the following articles: 1) "Chemical-Mechanical Polishing of Copper in Glycerol Based Slurries" (Materials Research Society Symposium Proceedings, 1996), Kumar et al.; 2) "Chemical-Mechanical Polishing of Copper with Oxide and Polymer Interlevel Dielectrics" (Thin Solid Films, 1995), Gutman et al.; 3) "Stabilization of Alumina Slurry for Chemical-Mechanical Polishing of Copper" (Langmuri, 1996) Lou et al.; 4) "Initial Study on Copper MCP Slurry Chemistries" (Thin Solid Films, 1995) Carpio et al.; 5)"Chemical-Mechanical Polishing of Copper for Interconnect Formation" (Microelectronic Engineering, 1997) Stavreva et al.

A copy of the following article is not enclosed because it is not in the possession of the undersigned: "Development of a 1:1:1 Slurry for Tantalum Layer Polishing" in proceedings of the CMP-MIC conference, February 1999.

It should be understood that attention has been called to the references that have been deemed to be pertinent to the claimed present invention. In concluding what was pertinent, the criteria employed was considered most appropriate in light of the

deem some other criteria to be just as appropriate or more appropriate. Therefore, the Examiner is respectfully urged to review the listed references and to make the usual careful independent search for other prior art that may be pertinent.

Respectfully submitted,

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AUG 3 2001

**TECHNOLOGY CENTER R3700** 

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